imall

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Panasonic

Zener Diode DZ2S130×0L

DZ2S130×0L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2J130 in SSMini2 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: SJ or SU

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C						
Parameter	Symbol	Rating	Unit			
Repetitive peak forward current	IFRM	200	mA			
Total power dissipation *1	PT	150	mW			
Electrostatic discharge ^{*2}	ESD	±8	kV			
Junction temperature	Tj	150	°C			
Operating ambient temperature	Topr	-40 to +85	°C			
Storage temperature	Tstg	-55 to +150	°C			

Note) *1 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm) Solder in (0.8 mm × 0.6 mm)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω , Contact discharge : 10 times)



*3 Tj = 25 °C to 150 °C

Electrical Characteristics $Ta = 25 \degree C \pm 3 \degree C$						
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	12.40		13.65	V
Zener operating resistance	RZ	IZ = 5 mA			35	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			80	Ω
Reverse current	IR	VR = 10 V			0.05	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		10.9		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

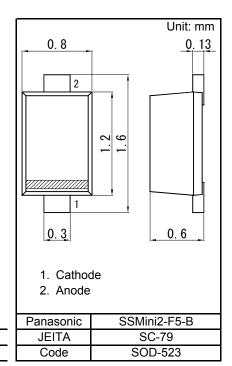
2. Absolute frequency of input and output is 5 MHz.

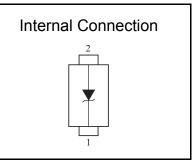
3. *1 The temperature must be controlled 25 °C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 °C).

*2 VZ guaranted 20 ms after current flow Rank classification

	Code	M M			0			
	Rank				No-rank			
	VZ	12.74	to	13.40	12.40	to	13.65	
	Marking symbol	SU		SJ				

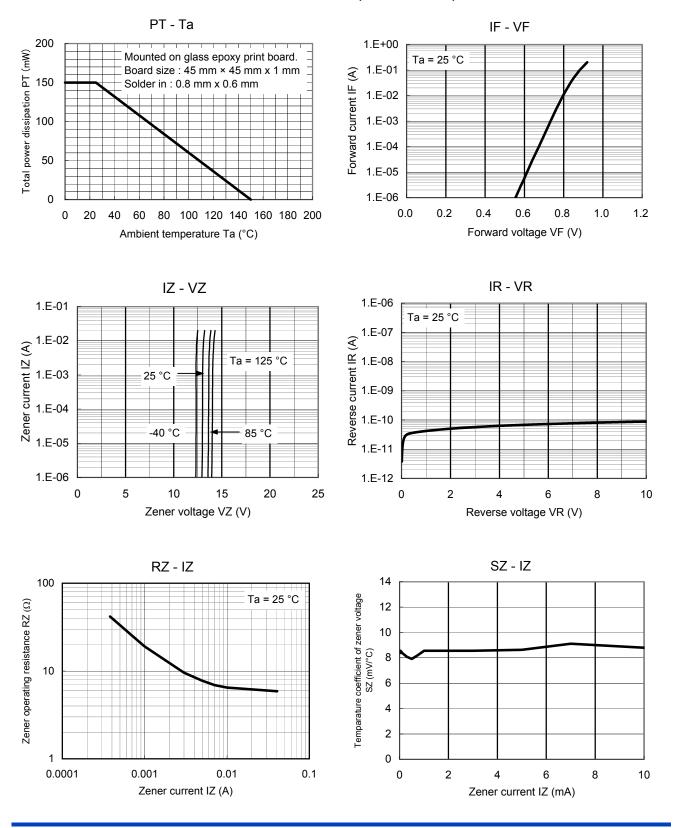






Zener Diode DZ2S130×0L

Technical Data (reference)



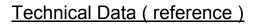
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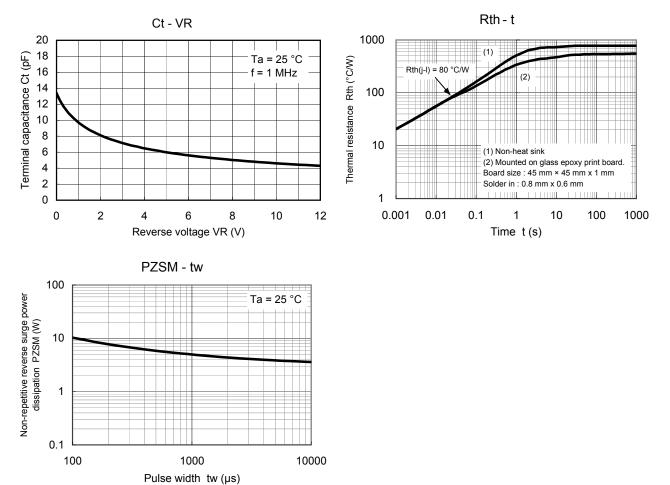
Established : 2009-11-10 Revised : 2013-07-23

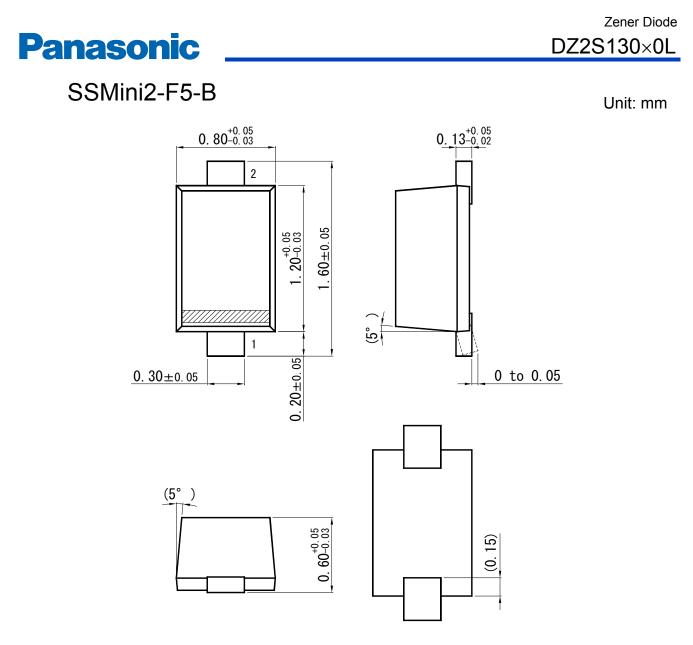




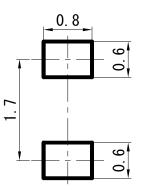
Zener Diode DZ2S130×0L







Land Pattern (Reference) (Unit: mm)



Established : 2009-11-10 Revised : 2013-07-23

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